

Integrated Device Technology, Inc. 6024 Silver Creek Valley Road, San Jose, CA - 95138

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PRODUCT/PROCESS CHANGE NOTICE (PCN)										
PCN #: A1811 Product Affected  Date Effective:		ecember 17, 2018	MEANS OF DISTI  □ Product Mark ■ Back Mark □ Date Code □ Date Code □ Other	NGUISHING CHANGI Lot # will have a '						
Contact:	IDT PCN DESK		Attachment:	Yes	☐ No					
E-mail:	pcndesk@idt.com		Samples:	Please contact your lo sample request & avai	cal sales representative for lability.					
DESCRIPTION  □ Die Technolo □ Wafer Fabrica □ Assembly Pro □ Equipment ■ Material □ Testing ■ Manufacturin □ Data Sheet □ Other	ation Process ocess	This notification is bump location on transferred from A discontinuing the Amkor Korea is c	in is to advise our customers that IDT is adding Amkor Korea as an alternate on the above products. In addition, the assembly location will also be a Amkor Philippines to Amkor Korea as a result of Amkor Philippines are assembly processes of these products.  So currently a qualified IDT Subcontractor.  Inge to the moisture performance rating.  Attachment 1 for the qualification summary and material set details.							
	QUALIFICATION SUMMARY s been successfully completed. The		SL rating.							
IDT records indi to grant approva it will be assume IDT reserves the	CKNOWLEDGMENT OF REC icate that you require written notifical or request additional information. ed that this change is acceptable. e right to ship either version manufarsion has been depleted.	cation of this change. If IDT does not recei	ve acknowledgemen	t within 30 days of this n						
Customer:		Appr	oval for shipmen	ts prior to effective	date.					
Name/Date: E-Mail Addr			ess:							
Title:	Phone# /Fax# :									
	LEDGMENT OF RECEIPT:		ATIC							
RECD. BY: DATE										

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# PRODUCT/PROCESS CHANGE NOTICE (PCN)

## **ATTACHMENT 1 - PCN #: A1811-01**

PCN Type: Add alternate Bump Location & Change Assembly Location & Assembly Material Sets

**Data Sheet Change:** N/A

## **Detail Of Change:**

This notification is to advise our customers that IDT is adding Amkor Korea as an alternate bump location on the above products. In addition, the assembly location will also be transferred from Amkor Philippines to Amkor Korea as a result of Amkor Philippines discontinuing the assembly processes of these products.

Amkor Korea is currently a qualified IDT Subcontractor.

There is no change in form, fit and function of the products including RoHS compliance and MSL rating.

IDT requests customers to respond to this notice within 30 days, with an indication if samples will be required. Samples must be placed within 30 days if required for qualification and approval to avoid any disruption in supply.

#### FCCSP-48: Qualified Material Sets, by Assembly Subcontractor

	Existing	New	
Die Bump Location	ATT - Amkor, Taiwan	ATT - Amkor, Taiwan and ATK - Amkor, Korea	
Material Set / Assembly	ATP - Amkor, Philippines	ATK - Amkor, Korea	
Die Bump	Sn1.8Ag	Sn1.8Ag	
Underfill Material	MUF-1	MUF-32	
Substrate	NVMUX 4L	NVMUX 4L	
Solder Balls	Sn96.5/Ag3.0/Cu0.5	Sn96.5/Ag3.0/Cu0.5	



# PRODUCT/PROCESS CHANGE NOTICE (PCN)

## **ATTACHMENT 1 - PCN # : A1811-01**

## **Qualification Information and Qualification Data:**

**Affected Packages:** FCCSP-48

**Assembly Material:** The affected package type is using the respective subcon standard materials as

shown on page 1 of this attachment. Qualification testing was completed on the

worse case package.

Qual Plan & Results: Tests are in accordance with JEDEC47 recommended tests

**Qualification Vehicle: FCCSP-48** (3 lots)

		Test Results (Rej/SS)			
Test Description	Test Method	Lot 1	Lot 2	Lot 3	
<sup>1</sup> HAST - biased (130 °C/85% RH, 96 Hrs)	JESD22-A110	0 / 25	0 / 25	0 / 25	
<sup>1</sup> HAST - unbiased (130 °C/85% RH, 96 Hrs)	JESD22-A118	0 / 25	0 / 25	0 / 25	
<sup>1</sup> Temperature Cycling (-55°C to 125°C, 700 cycles)	JESD22-A104	0 / 25	0 / 25	0 / 25	
High Temperature Storage Test (150°C, 1000 hours)	JESD22-A103	0 / 25	0 / 25	0 / 25	

Notes: 1. HAST and Temperature Cycle were subjected to Preconditioning per JESD22-A113 for MSL 3.